

NEGATIVE PHOTSENSITIVE RESIN COMPOSITION, NEGATIVE
PHOTSENSITIVE RESIN COMPOSITION COATING FILM, NEGATIVE
PHOTSENSITIVE RESIN COMPOSITION FILM, CURED FILM, AND ELECTRONIC
COMPONENT USING SAME

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ABSTRACT

A negative photosensitive resin composition comprising a cationic polymerizable compound as Component (A) and a photocationic polymerization initiator as Component (B), wherein Component (A) contains, as Component (A1), a polyfunctional aromatic glycidyl ether having an epoxy equivalent of 80 to 145 g/eq and having at least two or more epoxy groups in a molecule, and a content of Component (A1) in the total Component (A) is 45 to 100% by mass. Provided is a negative photosensitive resin composition suitable for bonding applications of semiconductor elements and electronic components, which achieves both excellent resolution and adhesion.

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No suitable figure